

Global Microelectronic Packaging Materials Supply, Demand and Key Producers, 2026-2032

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Abstracts

The global Microelectronic Packaging Materials market size is expected to reach \$ 48801 million by 2032, rising at a market growth of 7.5% CAGR during the forecast period (2026-2032).

In 2025, global Microelectronic Packaging Materials production reached approximately 380 K tons, with an average global market price of around 75 US\$/kg.

Microelectronic Packaging Materials are specialized materials used to protect, interconnect, insulate, support, and dissipate heat from semiconductor chips and microelectronic devices after wafer fabrication. They include package substrates, leadframes, ceramic packages, epoxy molding compounds, underfills, die attach pastes and films, solder materials, bonding wires, build-up films, encapsulants, thermal interface materials, EMI shielding materials, lids, sealants, and glass or ceramic interposers. These materials directly affect package reliability, electrical performance, heat dissipation, mechanical strength, moisture resistance, warpage control, miniaturization, and long-term device stability. They are widely used in IC packaging, advanced packaging, power modules, RF devices, MEMS, sensors, optoelectronics, automotive electronics, AI chips, high-performance computing, and consumer electronic components.

Demand for Microelectronic Packaging Materials is rising as semiconductor packaging shifts from simple chip protection toward high-density interconnection, heterogeneous integration, chiplet architecture, 2.5D/3D packaging, fan-out packaging, advanced substrates, and high-reliability power modules. AI servers, HBM, automotive electrification, 5G/6G communication, industrial automation, edge computing, wearable devices, and high-performance consumer electronics are increasing requirements for

low-loss substrates, low-warpage encapsulants, high-thermal-conductivity die attach, fine-pitch interconnect materials, and reliable underfill systems. Business opportunities are strongest in ABF/build-up materials, advanced package substrates, high-end epoxy molding compounds, sinter die attach materials, glass/ceramic substrates, thermal interface materials, and EMI shielding materials. Suppliers with formulation know-how, stable purity control, long qualification history, close cooperation with OSATs and IDMs, and capacity for localized supply chains will have stronger competitiveness.

This report studies the global Microelectronic Packaging Materials production, demand, key manufacturers, and key regions.

This report is a detailed and comprehensive analysis of the world market for Microelectronic Packaging Materials and provides market size (US\$ million) and Year-over-Year (YoY) Growth, considering 2025 as the base year. This report explores demand trends and competition, as well as details the characteristics of Microelectronic Packaging Materials that contribute to its increasing demand across many markets.

Highlights and key features of the study

Global Microelectronic Packaging Materials total production and demand, 2021-2032, (Kilotons)

Global Microelectronic Packaging Materials total production value, 2021-2032, (USD Million)

Global Microelectronic Packaging Materials production by region & country, production, value, CAGR, 2021-2032, (USD Million) & (Kilotons), (based on production site)

Global Microelectronic Packaging Materials consumption by region & country, CAGR, 2021-2032 & (Kilotons)

U.S. VS China: Microelectronic Packaging Materials domestic production, consumption, key domestic manufacturers and share

Global Microelectronic Packaging Materials production by manufacturer, production, price, value and market share 2021-2026, (USD Million) & (Kilotons)

Global Microelectronic Packaging Materials production by Material Function, production, value, CAGR, 2021-2032, (USD Million) & (Kilotons)

Global Microelectronic Packaging Materials production by Application, production, value, CAGR, 2021-2032, (USD Million) & (Kilotons)

This report profiles key players in the global Microelectronic Packaging Materials market based on the following parameters - company overview, production, value, price, gross margin, product portfolio, geographical presence, and key developments. Key

companies covered as a part of this study include Materion Corporation, Qnity Electronics, Panasonic Industry, Polymer Systems Technology Ltd., SCHOTT AG, Vibrantz Technologies, Mosaic Microsystems, Henkel Corporation, Sumitomo Bakelite Co., Ltd., Kyocera Corporation, etc.

This report also provides key insights about market drivers, restraints, opportunities, new product launches or approvals.

Stakeholders would have ease in decision-making through various strategy matrices used in analyzing the World Microelectronic Packaging Materials market

Detailed Segmentation:

Each section contains quantitative market data including market by value (US\$ Millions), volume (production, consumption) & (Kilotons) and average price (US\$/kg) by manufacturer, by Material Function, and by Application. Data is given for the years 2021-2032 by year with 2025 as the base year, 2026 as the estimate year, and 2027-2032 as the forecast year.

Global Microelectronic Packaging Materials Market, By Region:

United States

China

Europe

Japan

South Korea

ASEAN

India

Rest of World

Global Microelectronic Packaging Materials Market, Segmentation by Material Function:

Substrate and Interconnection Materials

Die Attach and Bonding Materials

Encapsulation and Protection Materials

Thermal and EMI Management Materials

Others

Global Microelectronic Packaging Materials Market, Segmentation by Package Technology:

Conventional IC Packaging Materials

Advanced Packaging Materials

Power Device Packaging Materials

RF and Optoelectronic Packaging Materials

Others

Global Microelectronic Packaging Materials Market, Segmentation by Thermal Conductivity Level:

Low Thermal Conductivity Materials: Below 1 W/m²K

Medium Thermal Conductivity Materials: 1-3 W/m²K

High Thermal Conductivity Materials: >3-10 W/m²K

Ultra-High Thermal Conductivity Materials: >10-50 W/m²K

Extreme Thermal Conductivity Materials: Above 50 W/m²K

Global Microelectronic Packaging Materials Market, Segmentation by Application:

Consumer Electronics

Automotive Electronics

Communication Infrastructure

Industrial Electronics

Medical Electronics

Aerospace and Defense Electronics

Others

Companies Profiled:

Materion Corporation

Qnity Electronics

Panasonic Industry

Polymer Systems Technology Ltd.

SCHOTT AG

Vibrantz Technologies

Mosaic Microsystems

Henkel Corporation

Sumitomo Bakelite Co., Ltd.

Kyocera Corporation

Indium Corporation

NAMICS Corporation

MacDermid Alpha Electronics Solutions

Ajinomoto Fine-Techno Co., Inc.

Resonac Corporation

Shin-Etsu Chemical Co., Ltd.

Ibiden Co., Ltd.

Shinko Electric Industries Co., Ltd.

TANAKA Precious Metals

Heraeus Electronics

Nitto Denko Corporation

Toray Industries, Inc.

Mitsui Chemicals, Inc.

AGC Inc.

Absolics

ASE Materials

Nan Ya PCB Corporation

Unimicron Technology Corporation

Ningbo Kangqiang Electronics Co., Ltd.

Shanghai Sinyang Semiconductor Materials Co., Ltd.

Nanya New Material Technology Co., Ltd.

Shenzhen FRD Science & Technology Co., Ltd.

Shenzhen HFC Co., Ltd.

SCIENCHEM Co., Ltd.

Key Questions Answered:

1. How big is the global Microelectronic Packaging Materials market?
2. What is the demand of the global Microelectronic Packaging Materials market?
3. What is the year over year growth of the global Microelectronic Packaging Materials market?
4. What is the production and production value of the global Microelectronic Packaging Materials market?
5. Who are the key producers in the global Microelectronic Packaging Materials market?
6. What are the growth factors driving the market demand?

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